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PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Yasuaki Tsuchiya, et al.

Examiner: Maria Guerrero

Serial No.: 09/737,397

Art Unit: 2822

Filed: December 15, 2000

Docket: 14162

For: PROCESS FOR FORMING A
METAL INTERCONNECT

Dated: July 26, 2002

Assistant Commissioner for Patents
Washington, D.C. 20231

TECHNOLOGY CENTER 2800
6/4/2002

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RESPONSE

Sir:

In response to the Office Action dated March 26, 2002, applicants submit the following amendment for entry in the above-identified case.

IN THE CLAIMS:

Please cancel Claim 29 without prejudice.

Please amend Claims 2, 12 and 28 as follows:

a 1
2. (Amended) The process for forming a metal interconnect as claimed in Claim 1, wherein the first polishing step is conducted such that the interconnect metal film remains in 5% to 30% inclusive of the surface area other than the concave.

*12/05
a 2*
12. (Amended) The process for forming a metal interconnect as claimed in

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner of Patents and Trademarks, Washington, D.C. 20231 on July 26, 2002.

Dated: July 26, 2002

Mishelle Mustafa